

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S14	5	257/774,698,780,738,758,783,778,779,701,773,777,668,734,666,678.ccls. and 438/108,114,118,612,613,106,107,614,125.ccls. and 324/755,765,701,754.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/18 10:46
S15	1478225	semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 15:46
S16	0	S15 and (external with contact with polimer with support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 15:49
S17	0	S15 and (external with contact with polimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 15:49
S18	16348	S15 and (external with contact)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 15:50
S19	386	S15 and ((external with contact) same polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 15:51
S20	150	S15 and (external with contact with polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/17 15:51
S21	11	S15 and (external with contact with polymer with support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/18 10:44
S22	1478225	semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/18 10:44

S23	11	S22 and (external with contact with polymer with support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/18 10:49
S24	37149	257,774,698,780,738,758,783, 778,779,701,773,777,668,734, 666,678.ccls. or 438/108,114,118, 612,613,106,107,614,125.ccls. or 324/755,765,701,754.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/18 12:03
S25	3	S24 and S23	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/18 10:47
S26	3	S24 and (external with contact with polymer with support)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/18 11:58
S27	4	((("6180504") or ("6118179")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 12:00
S28	0	"24" and (polymer external contact underfill)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2005/02/18 12:05
S29	2957	"24" and underfill	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2005/02/18 12:05
S30	55	semiconductor and underfill and polymer and (external contact)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/02/18 12:08